

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®

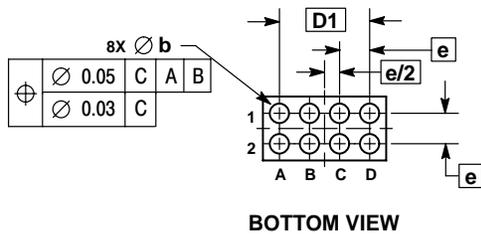
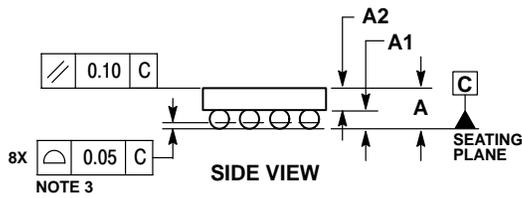
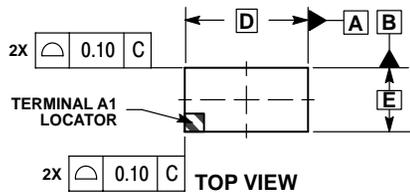


8 PIN FLIP-CHIP, 2.05x1.05, 0.5P CASE 766AE-01 ISSUE C



SCALE 4:1

DATE 06 NOV 2006



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.655
A1	0.210	0.270
A2	0.335	0.385
b	0.290	0.340
D	2.050 BSC	
D1	1.500 BSC	
E	1.050 BSC	
e	0.500 BSC	

GENERIC MARKING DIAGRAM*



A1

- XXXXXXXX = Specific Device Code
- = Pb-Free Device
- A = Assembly Location
- Y = Year
- WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	8 PIN FLIP-CHIP, 2.05X1.05, 0.5P	PAGE 1 OF 2

